

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) A thin IC tag, comprising:

a product obtained by (i) forming an electronic part holding film by mounting an electronic part on a flexible sheet on which an antenna coil is formed, and then (ii) folding the electronic part holding film in one direction such that the electronic part holding film is divided into sections having substantially an identical size,

the electronic part being provided on a circuit board, being provided in the electronic part holding film as an electronic part module,

the sections of the electronic part holding film respectively having winding conductor patterns each formed on at least one surface of each of the sections such that respective centers of the winding conductor patterns match each other when the electronic part holding film is folded,

the winding conductor patterns respectively formed on the sections constituting the antenna coil in which the winding conductor patterns are serially connected to each other via a predetermined connecting part so that a current flows in one winding direction when the electronic part holding film is folded,

the winding conductor patterns provided in the sections having ends in which terminal pads are formed and to which the predetermined connecting part is not connected, respectively, the terminal pads of the winding conductor patterns whose centers match each other when the electronic part holding film is folded being electrically connected to each other via the electronic part module,

~~the electronic part module being provided on the electronic part holding film so as to bridge across a circulation conductor bundle which constitutes the winding conductor patterns whose centers match each other when the electronic part holding film is folded; and~~

~~the electronic part module being formed so as to be folded when the electronic part holding film is folded.~~

2. (Original) The thin IC tag as set forth in claim 1, wherein:

the electronic part module is provided on the electronic part holding film so as to bridge across a circulation conductor bundle which constitutes the winding conductor patterns whose centers match each other when the electronic part holding film is folded; and

the electronic part module is formed so as to be folded when the electronic part holding film is folded.

3. (Original) The thin IC tag as set forth in claim 1, wherein the terminal pads are provided inside portions surrounded by the winding conductor patterns provided in the sections, respectively.

4. (Original) A method for manufacturing the thin IC tag as set forth in claim 1, the method comprising:

a first step of forming an electronic part holding film by providing, on (i) a flexible sheet on which an antenna coil is formed, (ii) an electronic part module in which an electronic part is mounted on a circuit board;

a second step of forming an adhesion layer on at least one surface of the electronic part holding film; and

a third step of folding the electronic part holding film on which the adhesion layer has been formed in the second step.

5. (Original) A method for manufacturing the thin IC tag as set forth in claim 1, the method comprising:

a first step of forming an electronic part holding film by providing, on (i) a flexible sheet on which an antenna coil is formed, (ii) an electronic part module in which an electronic part is mounted on a circuit board;

a second step of bonding the electronic part module to the flexible sheet on which the antenna coil is formed;

a third step of forming an adhesion layer on at least one surface of the electronic part holding film; and

a fourth step of folding the electronic part holding film on which the adhesion layer has been formed in the third step.

6. (Currently amended) The method as set forth in claim ~~4~~ or 5, further comprising the step of forming, at a folding position at which the electronic part holding film is folded, a folding mark allowing the electronic part holding film to be folded easily, the step being carried out before the step of folding the electronic part holding film.

7. (Original) The method as set forth in claim 6, wherein the step of forming the folding mark includes the step of making a cut line by using a laser.

8. (New) The method as set forth in claim 5, further comprising the step of forming, at a folding position at which the electronic part holding film is folded, a folding mark allowing the electronic part holding film to be folded easily, the step being carried out before the step of folding the electronic part holding film.